



SOT917-6(DD)

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wettable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

7 July 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN20
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	24-06-2022
Manufacturer package code	98ASA01574D

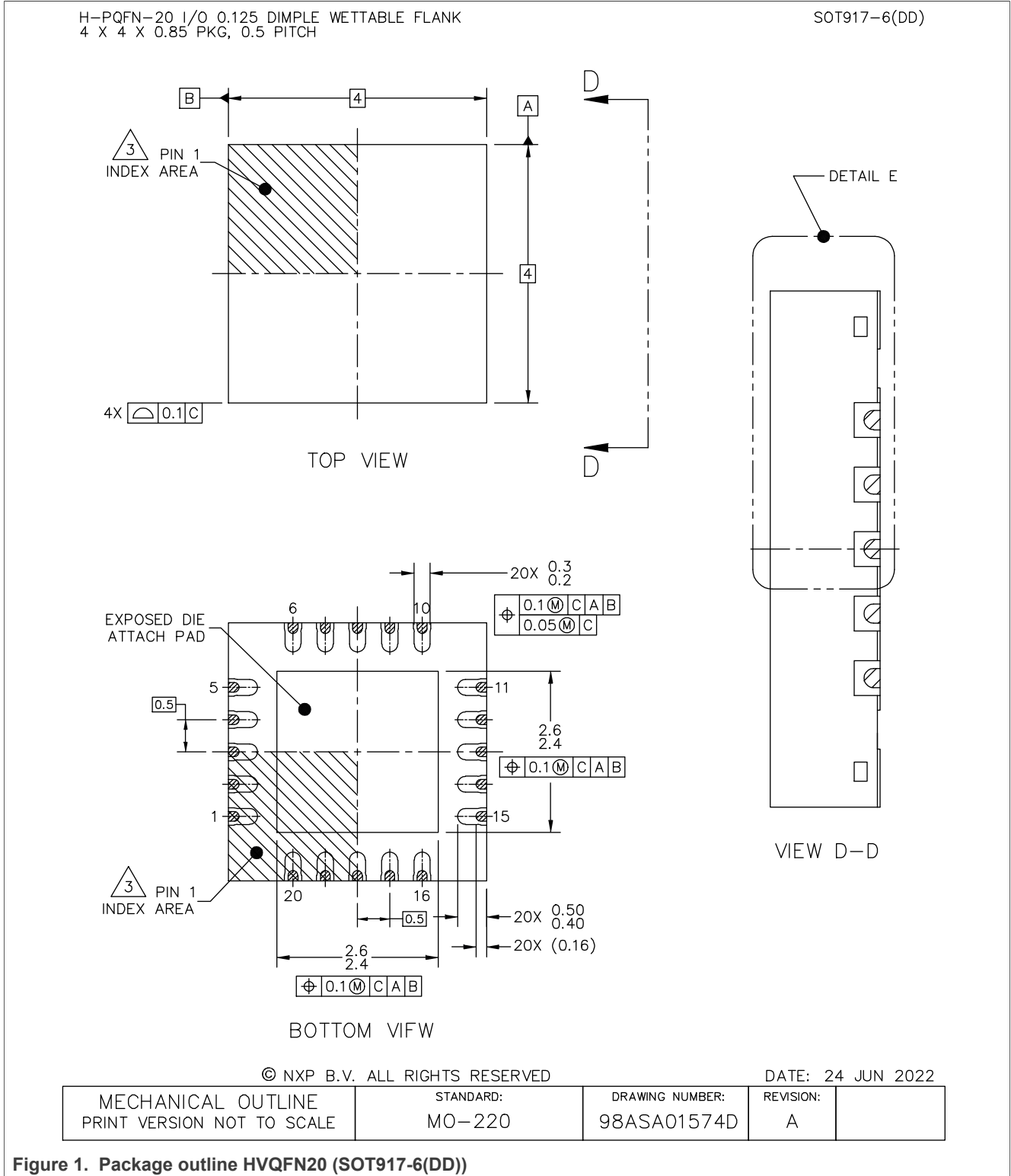
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	20	-	



HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wettable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

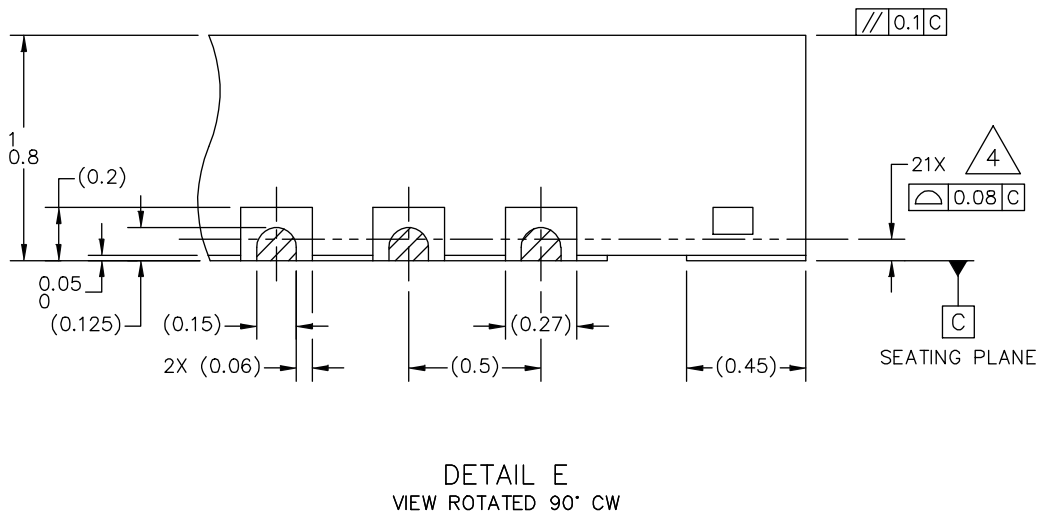
2 Package outline



HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wettable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O 0.125 DIMPLE WETTABLE FLANK
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-6(DD)



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DATE: 24 JUN 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-220	DRAWING NUMBER: 98ASA01574D	REVISION: A
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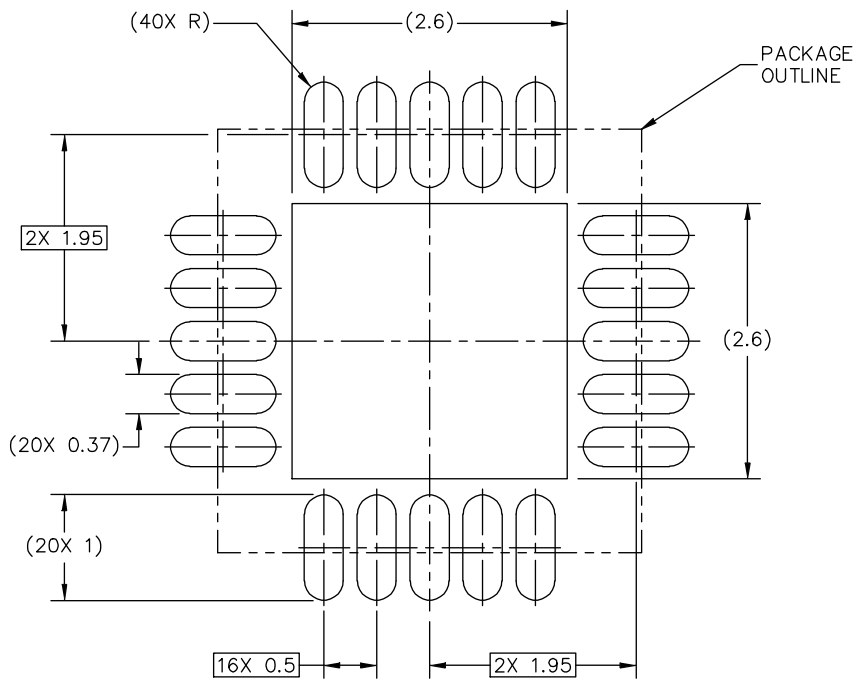
Figure 2. Package outline detail of HVQFN20 (SOT917-6(DD))

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wetable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

3 Soldering

H-PQFN-20 I/O 0.125 DIMPLE WETTABLE FLANK
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-6(DD)



PCB DESIGN GUIDELINES
RECOMMENDED SOLDER MASK OPENING PATTERN

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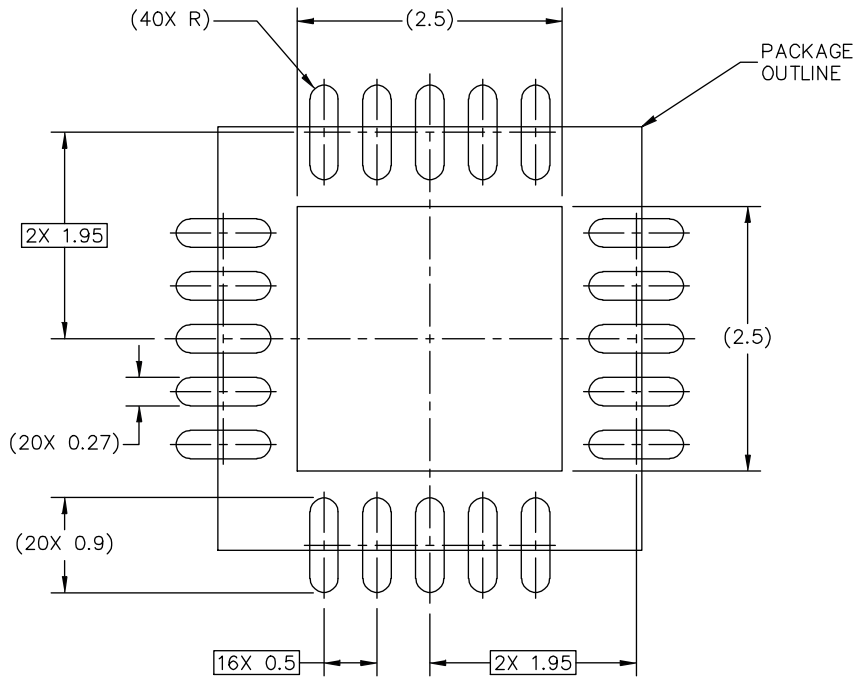
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Figure 3. Reflow soldering footprint part1 for HVQFN20 (SOT917-6(DD))

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H-PQFN-20 I/O 0.125 DIMPLE WETTABLE FLANK
4 X 4 X 0.85 PKG, 0.5 PITCH

SOT917-6(DD)



PCB DESIGN GUIDELINES
RECOMMENDED I/O PADS AND SOLDERABLE AREA

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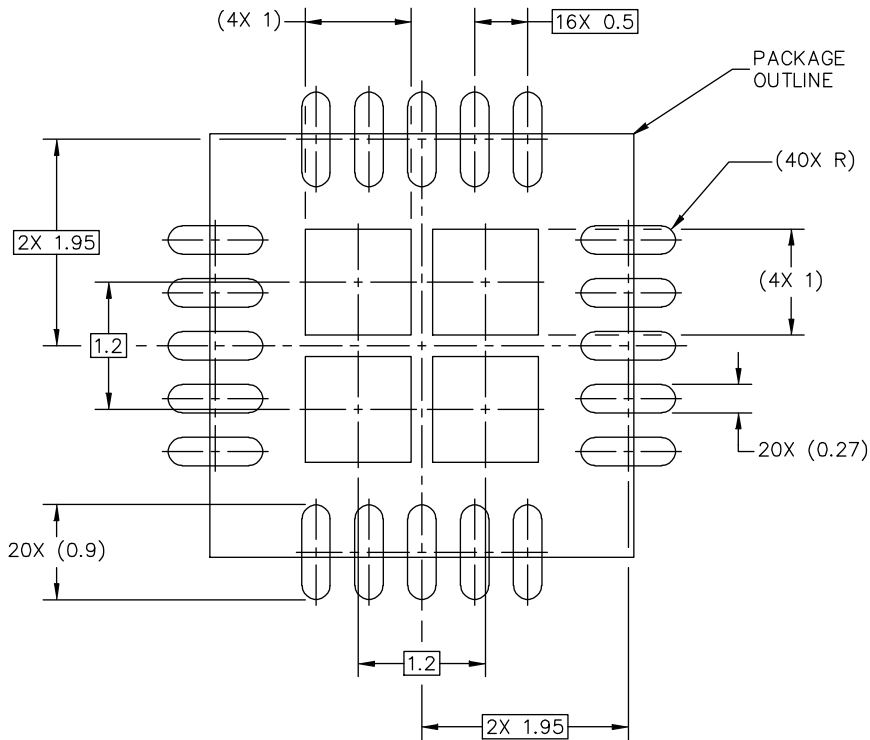
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Figure 4. Reflow soldering footprint part2 for HVQFN20 (SOT917-6(DD))

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wettable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O 0.125 DIMPLE WETTABLE FLANK
4 X 4 X 0.85 PKG, 0.5 PITCH

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RECOMMENDED STENCIL THICKNESS 0.125 OR 0.150

PCB DESIGN GUIDELINES – RECOMMENDED SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVQFN20 (SOT917-6(DD))

HVQFN20, plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; 0.125 dimple wettable flank, 0.5 mm pitch, 4 mm x 4 mm 0.85 mm body

H-PQFN-20 I/O 0.125 DIMPLE WETTABLE FLANK
4 X 4 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 6. Package outline note HVQFN20 (SOT917-6(DD))

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4 Legal information

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